

In re Patent Application of
RAYNOR
Serial No. Not Yet Assigned
Filed: Herewith

In the Specification:

Please replace paragraph [0005] on page 2 with the following rewritten paragraph:

~~According to a first aspect of the present invention, there is provided a method of attaching a sensor and a housing to opposite sides of a stratum as set out in Claim 1 of the attached claims.~~ A first aspect of the present invention is directed to a method of attaching a sensor and a housing to opposite sides of a mounting substrate. The sensor may have a sensing face comprising a sensing area and at least one signal output contact thereon. The substrate may have a circuitry face and at least one signal input contact thereon. The mounting substrate may also have an opening therethrough. The method may comprise positioning the sensing area over the opening so that the at least one signal output contact of the sensor contacts the at least one signal input contact of the mounting substrate. The housing may be positioned for contacting the mounting substrate so that the housing and the sensor are in alignment.

Please replace paragraph [0006] on page 2 with the following rewritten paragraph:

~~According to a second aspect of the present invention, there is provided a method of attaching a sensor to a stratum as set out in Claim 2 of the attached claims.~~ A second aspect of the present invention is directed to a method of attaching a sensor to a mounting substrate. The sensor may have a sensing face comprising a sensing area and at least one signal output contact thereon. The mounting substrate may

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have a circuitry face and at least one signal input contact thereon. The mounting substrate may also have an opening therethrough. The method may comprise positioning the sensing area over the opening so that the at least one signal output contact contacts the at least one signal input contact of the mounting substrate.

Please replace paragraph [0007] on pages 2-3 with the following rewritten paragraph:

~~According to a third aspect of the present invention, there is provided an aligned sensor package as set out in Claim 21 of the attached claims.~~ A third aspect of the present invention is directed to a sensor package comprising a mounting substrate having a circuitry face and at least one signal input contact thereon. The mounting substrate may also have an opening therethrough. A sensor may be on the circuitry face side of the mounting substrate and has a sensing face comprising a sensing area and at least one signal output contact thereon. The sensing area is over the opening so that the at least one signal output contact contacts the at least one signal input contact of the mounting substrate. A housing is on a back side of the mounting substrate opposite the circuitry face side and is aligned with said sensor.